

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	IPD/16/9687	
<b>1.3 Title of PCN</b>	SO8 HIGH-DENSITY ASSEMBLY LINE AND NEW MATERIAL SET IN ST BOUSKOURA FOR IPD-IPC PRODUCTS	
<b>1.4 Product Category</b>	Products housed in package SO8	
<b>1.5 Issue date</b>	2016-03-22	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	ROBERTSON HEATHER
<b>2.1.2 Phone</b>	+1 8475853058
<b>2.1.3 Email</b>	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Maria Rosa BORGHI
<b>2.1.2 Marketing Manager</b>	Francesca Marta SANDRINI, Emanuele VAVASSORI
<b>2.1.3 Quality Manager</b>	Paolo MORETTI

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Materials	New direct material part number (same supplier, different supplier or new supplier), lead frame, resin, wire, ?)	ST Bouskoura (Morocco)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Product lines like 0303, UE27 and U093 are assembled in Bouskoura on HD line using molding compound G630AY.  Product lines like SL01 are assembled in Bouskoura on SOSA line using molding compound MP8000CH4.	Product lines like 0303, UE27 and U093 will be assembled in Bouskoura on HD line using molding compound G700KC.  Product lines like SL01 will be assembled in Bouskoura on HD line using molding compound G700KC.
<b>4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?</b>	No impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Process standardization and capacity increase
<b>5.2 Customer Benefit</b>	CAPACITY INCREASE

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	By a new Finished Goods code
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2016-03-02
<b>7.2 Intended start of delivery</b>	2016-05-31
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	UE27 Reliability Report.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2016-03-22

**9. Attachments (additional documentations)**

9687PpPrdtLst.pdf  
 PCN SO8\_BSK\_HDLINE\_NEWMOLDING.pdf  
 UE27 Reliability Report.pdf  
 SO8 BSK HD new BOM - UE27-U093-0303\_.pptx

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
L6561D013TR	L6561D013TR	
	L6562AD	
	L6562ADTR	
	L6562ATD	
	L6562ATDTR	
L6562DTR	L6562DTR	
L6565D	L6565D	
L6565DTR	L6565DTR	
	TSM101ACD	
	TSM101ACDT	
	TSM103WIDT	
	UC2843BD1	
	UC2844BD1	
	UC2845BD1	
	UC2845BD1013TR	
	UC3843BD1	
	UC3843BD1013TR	
	UC3844BD1013TR	
	UC3845BD1013TR	

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## Public Products List

**PCN Title :** SO8 HIGH-DENSITY ASSEMBLY LINE AND NEW MATERIAL SET IN ST BOUSKOURA FOR IPD-IPC PRODUCTS

**PCN Reference :** IPD/16/9687

**PCN Created on :** 02-Mar-2016

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

UC2844BD1013TR	UC3842BD1	UC3845BD1013TR
L6562ATDTR	L6565D	UC2845BD1013TR
L6562D	TSM101CD	UC2842BD1013TR
L6562DTR	UC3845BD1	UC2845BD1
TSM103WAID	TSM103WID	L6562ATD
UC3844BD1013TR	UC2843BD1	TSM103WIDT
TSM101ACDT	UC3842BD1013TR	UC2844BD1
UC2843BD1013TR	UC3844BD1	L6565DTR
TSM101ACD	UC3843BD1013TR	UC3843BD1
L6561D013TR	L6562ADTR	UC2842BD1
HVLED002	TSM103WAIDT	TSM101CDT
L6562AD	HVLED002TR	TSM101AID
TSM101IDT	TSM101AIDT	TSM101ID
L6561D		



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